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What is claimed is:

A multiple wavelength surface-emitting laser device comprising:

a substrate; and

a plurality of surface-emitting lasers that are formed on the substrate by a continuous manufacturing process,

wherein each of said plurality of surface-emitting lasers comprises:

a bottom reflection layer on the substrate, that is doped with impurities of a first type and that is composed of alternating semiconductor material layers having different refractive indexes;

an active layer that is formed on the bottom reflection layer; an intermediate layer that is doped with impurities of a second type on the active layer;

a top electrode that is formed on the intermediate layer to have a window through which light is emitted; and

a dielectric reflection layer where dielectric materials with different refractive indexes are alternately layered on at least one of the intermediate layer and the top electrode to a thickness suitable for a desired resonance wavelength, which is controlled by adjusting the thickness of the dielectric reflection layer.

2. The multiple wavelength surface-emitting laser of claim 1, wherein the dielectric reflection layer is composed of two different dielectric materials with different refractive indexes.

3. The multiple wavelength surface-emitting laser of claim 2, wherein the dielectric reflection layer is composed of any two dielectric materials selected from the group consisting of TiO₂, Ta₂O₅, ZrO₂, HfO, SiO₂ and MgF₂.

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- 4. The multiple wavelength surface-emitting laser of claim 1, wherein the dielectric reflection layer is composed of any two dielectric materials selected from the group consisting of TiO₂, Ta₂O₅, ZrO₂, HfO, SiO₂ and MgF₂.
- 5 The multiple wavelength surface-emitting laser device of claim 1 further comprising a high resistance part that confines electric current between the active layer and the top electrode.
- 6. A method of manufacturing a multiple wavelength surface-emitting laser device, comprising the steps of

sequentially forming, on a prepared substrate, a bottom reflection layer, that is doped with impurities of a first type and composed of alternating semiconductor material layers having different refractive indexes, an active layer and an intermediate layer that is doped with impurities of a second type;

forming an arrangement of a plurality of surface-emitting lasers by removing the intermediate layer, the active layer and a part of the bottom reflection layer by etching;

forming, on the intermediate layer of each surface-emitting laser, a top electrode having a window through which light is emitted; and

forming, on at least one of the intermediate layer and the top electrode of each surface-emitting laser, a dielectric reflection layer where different dielectric materials are alternately layered to a thickness suitable for a desired resonance wavelength.

- 7. The method of manufacturing a multiple wavelength surface-emitting laser device of claim 6, wherein the dielectric reflection layer is composed of two different dielectric materials with different refractive indexes.
 - 8. The method of manufacturing the multiple wavelength surface-emitting

laser device of claim 7, wherein the dielectric reflection layer is composed of any two dielectric materials selected from the group consisting of TiO₂, Ta₂O₅, ZrO₂, HfO, SiO₂ and MgF₂.

- 9. The method of manufacturing the multiple wavelength surface-emitting laser device of claim 7, wherein the dielectric reflection layer is formed by using an optical deposition unit.
- 10. The method of manufacturing the multiple wavelength surface-emitting laser of claim 6, wherein the dielectric reflection layer is composed of any two dielectric materials selected from the group consisting of TiO₂, Ta₂O₅, ZrO₂, HfO, SiO₂ and MgF₂.
- 11. The method of manufacturing the multiple wavelength surface-emitting laser device of claim 6, wherein the dielectric reflection layer is formed by using an optical deposition system.
- 12. The method of manufacturing the multiple wavelength surface-emitting laser of claim 6 further comprising a step of forming a high resistance part that confines electric current between the active layer and the top electrode.

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